技术数据表

## 特点（F ）：

* L/W/H :1.6*0.8*0.6 mm

Outline Dimensions (L / w / h): 1.6 x 0.8 x 0.6mm

* : 940nm/

Color and colloid: infrared emission 940nm / transparent colloid

* ROHS

Environmental protection products Complied With ROHS Directive

* MSL :3

Moisture sensitivity level MSL : 3 levels

* EIA

EIA standard packaging

* SMT

Suitable for SMT automatic production

*

Suitable for infrared reflow soldering process

## 应用领域（P ）：

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Medical equipmen

*

Infrared remote controller

*

Camera monitoring head

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Industrial control: counters, thermal imaging, smart meter

*

Infrared photoelectric switch

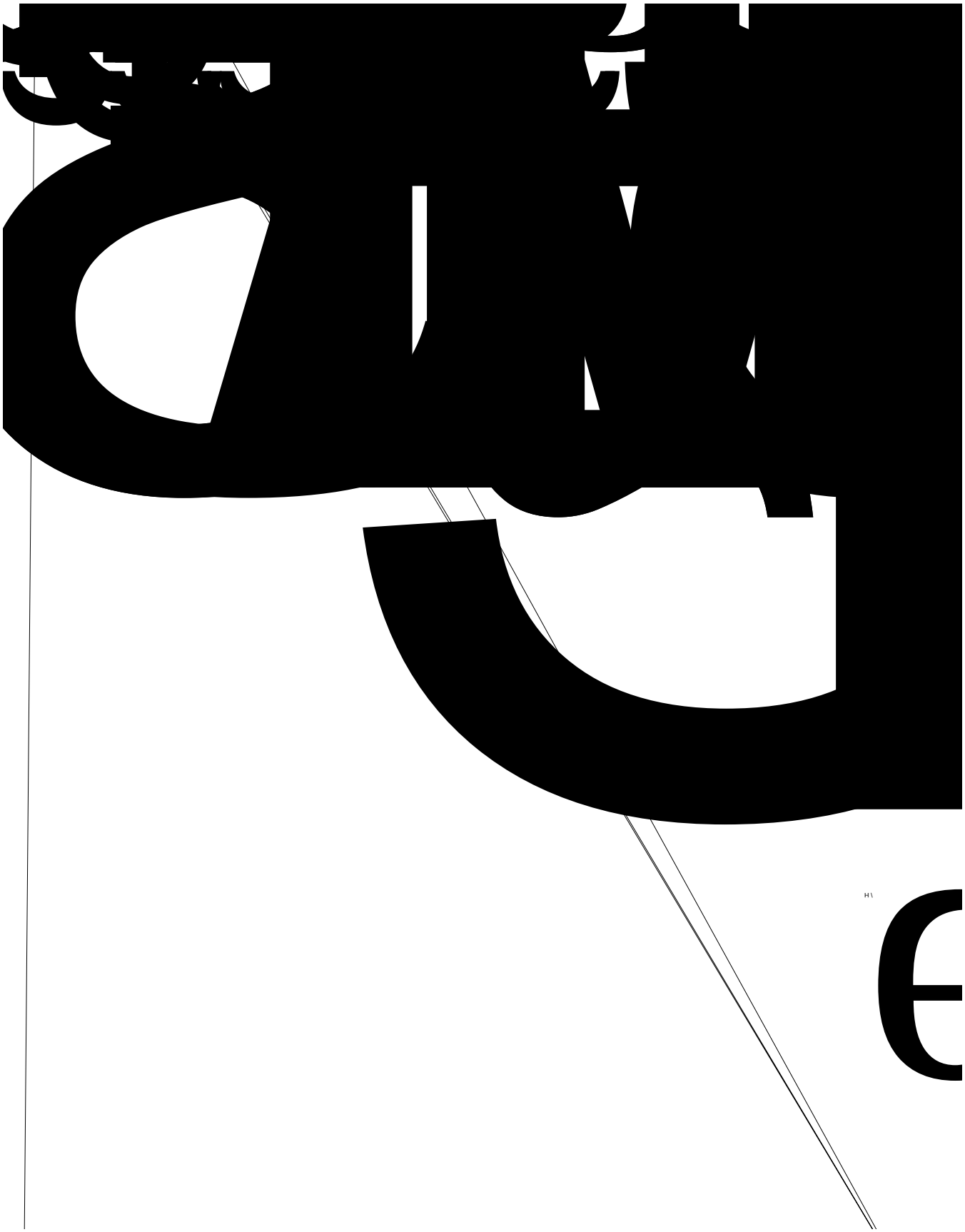
*

Wireless communication and sig nicc Ş ή

# 可靠性试验

## Reliability Test Items And Conditions

| Class | Test item | Testing environment | Testing time | Reference standard |
|---|---|---|---|---|
| Endurance test | Working life | 20mA Continuous lighting at the maximum rated current at room | 1000 1000 hours -24 +72 ) -24hours +72hours | MIL-STD-750D:1026<br>MIL-STD-883D:1005<br>JIS C 7021:B-1 |
| | High temperature and high humidity storage | IR-Reflow In-Board, 2 Times Ta= 85±5 , RH= 90 95% | 240 240hours ±2 ) ± 2hours) | MIL-STD-202F:103B<br>JIS C 7021:B-11 |
| | High-temperature storage | Ta= 85±5 | 1000 1000 hours -24 +72 ) -24hours+72hours | MIL-STD-883D:1008<br>JIS C 7021:B-10 |
| | Low temperature | Ta= -40±5 | | JIS C 7021:B-12 |
| Environmental testing | Cold and hot cycle | 105 25 -55 25 30mins 5mins 30mins 5mins | 100 100 Circles | MIL-STD-202F:107D<br>MIL-STD-750D:1051<br>MIL-STD-883D:1010 |
| | Hot and cold impact | IR-Reflow In-Board, 2 Times 100± 5 -40 ± 5 20mins 20mins | 100 100 Circles | MIL-STD-202F:107D<br>MIL-STD-750D:1051<br>MIL-STD-883D:1011 |
| | Anti-tin test | T.sol= 260 ± 5 | 10 ± 1secs 2 2times | MIL-STD-202F:210A<br>MIL-STD-750D:2031 |
| | Infrared reflowwelding There is lead process | heat up speed(183 ) 3 / keep temperature 125(±25) 120 keep temperature 183 60-150 maximum temperature 235 +5/-0 keep 235 +5/-0 10-15 cooling rate 6 / | -------- | MIL-STD-750D:2031.2<br>J-STD-020C |
| | Infrared reflow welding Lead-free process | heat up speed(217 ) 3 / keep temperature 175(±25) 180 keep temperature 217 60-120 maximum temperature 255 +0/-5 keep 255 +0/-5 5-10 cooling rate 6 / | -------- | MIL-STD-750D:2031.2<br>J-STD-020C |
| | Weldability test | Soldering temperature T.sol= 235 ± 5 Immersion speed 25±2.5 mm/ 95% Tin loading rate ≥ 95% pad area Immersion time: 2 ± 0.5 seconds | Immersion time 2± 0.5 | MIL-STD-202F:208D<br>MIL-STD-750D:2026<br>MIL-STD-883D:2003<br>IEC 68 Part 2-20<br>JIS C 7021:A-2 |

## 使用注意事项（2）

Precautions (2)